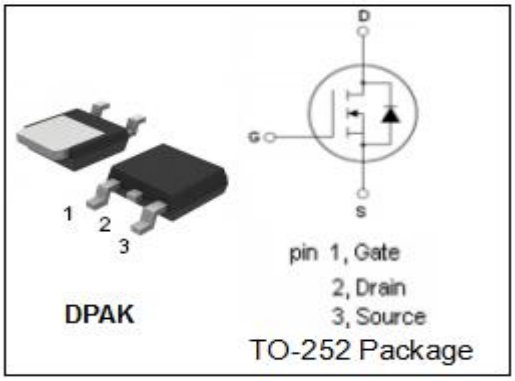
isc N-Channel MOSFET Transistor FQD13N10

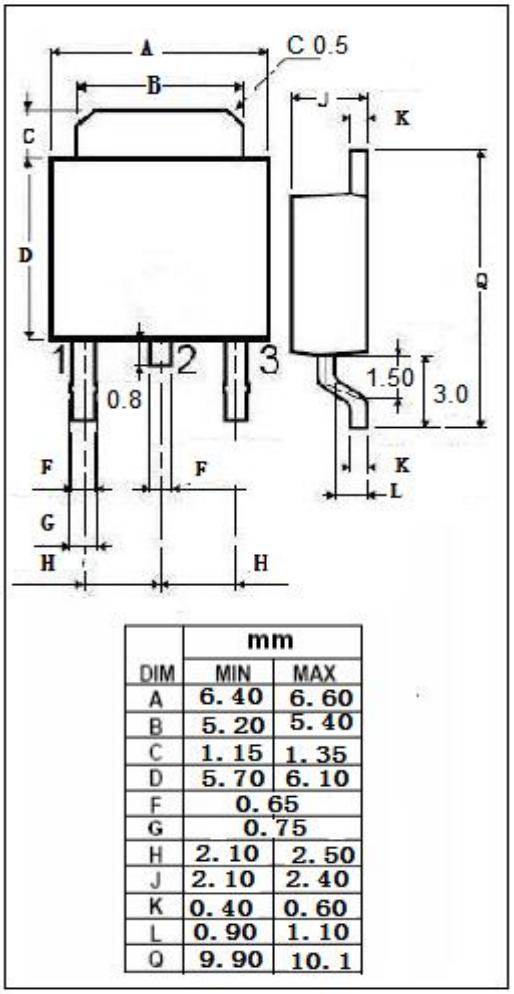


• FEATURES

- Static drain-source on-resistance:
  $R_{DS(on)} \leqslant 0.18\Omega$
- 100% avalanche tested
- Minimum Lot-to-Lot variations for robust device performance and reliable operation

• DESCRIPTION

- Switching applications



DIM	mm MIN	MAX
A	6.40	6.60
B	5.20	5.40
C	1.15	1.35
D	5.70	6.10
F	0.65	
G	0.75	
H	2.10	2.50
J	2.10	2.40
K	0.40	0.60
L	0.90	1.10
Q	9.90	10.1

• ABSOLUTE MAXIMUM RATINGS(T_a=25℃)

SYMBOL	PARAMETER	VALUE	UNIT
V_{DSS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	±25	V
I_D	Drain Current-Continuous	10	A
I_{DM}	Drain Current-Single Pulsed	40	A
P_D	Total Dissipation @T_C=25℃	40	W
T_j	Max. Operating Junction Temperature	150	℃
T_{stg}	Storage Temperature	-55~150	℃

• THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
Rth(j-c)	Channel-to-case thermal resistance	3.1	℃/W

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ELECTRICAL CHARACTERISTICS

T_C=25℃ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V; I_D=250 μA	100			V
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}; I_D=250 μA	2		4	V
$R_{DS(on)}$	Drain-Source On-Resistance	V_{GS}=10V; I_D=5A			0.18	Ω
I_{GSS}	Gate-Source Leakage Current	V_{GS}= ±25V			±100	nA
I_{DSS}	Drain-Source Leakage Current	V_{DS}= 100V; V_{GS}= 0V			1	μA
		V_{DS}= 80V; V_{GS}= 0V;T_C=125℃			10	μA
V_{SD}	Diode forward voltage	I_{SD}= 10A, V_{GS} = 0V			1.5	V